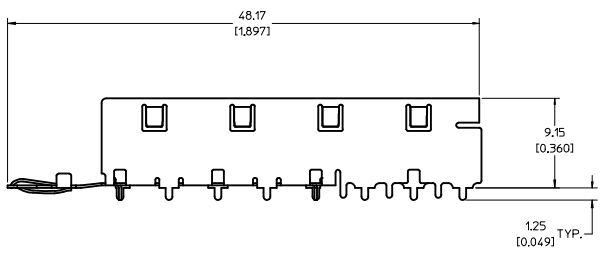
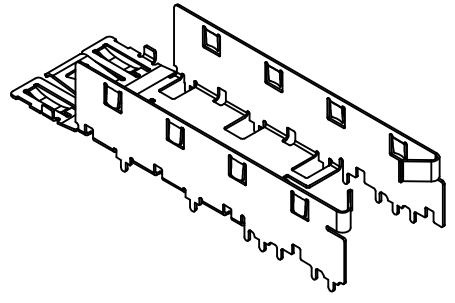
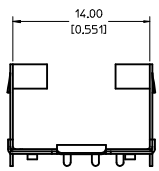
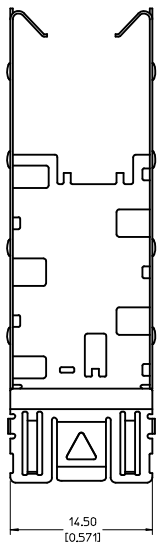


NOTES:

1. MATERIAL: COPPER ALLOY
2. PLATING: BRIGHT TIN
2.54 MICROMETERS TIN (MIN)
OVER 0.76 MICROMETERS (MIN) NICKEL
3. FOR DETAILS OF PCB AND BEZEL LAYOUT REFER TO DOCUMENT SD-73927-100.
4. THIS PRODUCT NOT INTENDED FOR LEAD FREE, (RoHS), REFLOW PROCESS. REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C
5. FOR RoHS COMPLIANT REPLACEMENTS REFER TO MOLEX SERIES 74737.

ENTER DESCRIPTION EC NO: UST2006-0264 DRAWN BY: DRWNSKIMONSON 2006/07/03 CHECKED BY: CHFKBRUSSELL 2006/07/06 APPR: BRUSSELL 2006/07/24	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▼=0 ▽=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .005 2 PLACES ± 0.13 ± .01 1 PLACE ± 0.25 ± --- ANGULAR ± 1 °	MM/IN	4:1	METRIC	DRAWN BY: KS IMONSON 2005/10/12 CHECKED BY: BRUSSELL 2005/10/12 APPROVED BY: BRUSSELL 2005/10/12
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO: 739270040	DOCUMENT NO: SD-73927-0040	SHEET NO: 1 OF 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

20 19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1



NOTES:

1. MATERIAL: COPPER ALLOY
2. PLATING: BRIGHT TIN
2.54 MICROMETERS TIN (MIN)
OVER 0.76 MICROMETERS (MIN) NICKEL
3. FOR DETAILS OF PCB AND BEZEL LAYOUT REFER TO DOCUMENT SD-73927-100.
4. THIS PRODUCT NOT INTENDED FOR LEAD FREE, REFLOW PROCESS. REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C. FOR REFLOW PROCESSES GREATER THAN 180°C, REFER TO MOLEX SERIES 74737.

ENTER DESCRIPTION IEC NO: 2006/07/29 DRAWN: COX CHKD: 2006/08/07 APPR: BRUSSELL 2006/08/15 REV: DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0 ▽=0	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± .005 2 PLACES ± 0.13 ± .01 1 PLACE ± 0.25 ± --- ANGULAR ± 1 °	MM/IN	4:1	METRIC	DRAWN BY: KS IMONSON DATE: 2005/10/12 CHECKED BY: BRUSSELL DATE: 2005/10/12 APPROVED BY: BRUSSELL DATE: 2005/10/12	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 739270040		DOCUMENT NO. SD-73927-040		TITLE SFP CAGE BASE SOLDER POSTS FOR WAVE SOLDER
			MOLEX INCORPORATED		SHEET NO. 1 OF 1		

19 18 17 16 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1